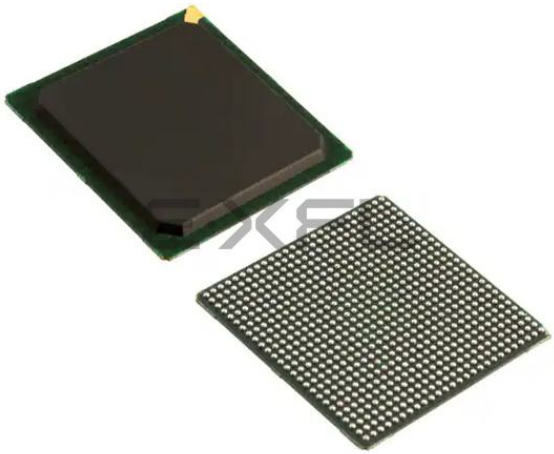

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	18144
Number of Logic Elements/Cells	-
Total RAM Bits	165888
Number of I/O	418
Number of Gates	1000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TA)
Package / Case	676-BGA
Supplier Device Package	676-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax1000-fgg676

Packaging Data

Refer to the following documents located on the Microsemi SoC Products Group website for additional packaging information.

- Package Mechanical Drawings
- Package Thermal Characteristics and Weights
- Hermatic Package Mechanical Information

Contact your local Microsemi representative for device availability.

The maximum power dissipation allowed for Military temperature and Mil-Std 883B devices is specified as a function of θ_{jc}.

Table 2-6 • **Package Thermal Characteristics**

Package Type	Pin Count	θ_{jc}	θ_{ja} Still Air	θ_{ja} 1.0m/s	θ_{ja} 2.5m/s	Units
Chip Scale Package (CSP)	180	N/A	57.8	51.0	50	°C/W
Plastic Quad Flat Pack (PQFP)	208	8.0	26	23.5	20.9	°C/W
Plastic Ball Grid Array (PBGA)	729	2.2	13.7	10.6	9.6	°C/W
Fine Pitch Ball Grid Array (FBGA)	256	3.0	26.6	22.8	21.5	°C/W
Fine Pitch Ball Grid Array (FBGA)	324	3.0	25.8	22.1	20.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	484	3.2	20.5	17.0	15.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	676	3.2	16.4	13.0	12.0	°C/W
Fine Pitch Ball Grid Array (FBGA)	896	2.4	13.6	10.4	9.4	°C/W
Fine Pitch Ball Grid Array (FBGA)	1152	1.8	12.0	8.9	7.9	°C/W
Ceramic Quad Flat Pack (CQFP)[1]	208	2.0	22	19.8	18.0	°C/W
Ceramic Quad Flat Pack (CQFP)[1]	352	2.0	17.9	16.1	14.7	°C/W
Ceramic Column Grid Array (CCGA)[2]	624	6.5	8.9	8.5	8	°C/W

Notes:

1. *θ_{jc} for the 208-pin and 352-pin CQFP refers to the thermal resistance between the junction and the bottom of the package.*
2. *θ_{jc} for the 624-pin CCGA refers to the thermal resistance between the junction and the top surface of the package. Thermal resistance from junction to board (θ_{jb}) for CCGA 624 package is 3.4°C/W.*

Timing Characteristics

Axcelerator devices are manufactured in a CMOS process, therefore, device performance varies according to temperature, voltage, and process variations. Minimum timing parameters reflect maximum operating voltage, minimum operating temperature, and best-case processing. Maximum timing parameters reflect minimum operating voltage, maximum operating temperature, and worst-case processing. The derating factors shown in Table 2-7 should be applied to all timing data contained within this datasheet.

Table 2-7 • **Temperature and Voltage Timing Derating Factors (Normalized to Worst-Case Commercial, T_J = 70°C, VCCA = 1.425V)**

	Junction Temperature						
VCCA	–55°C	–40°C	0°C	25°C	70°C	85°C	125°C
1.4 V	0.83	0.86	0.91	0.96	1.02	1.05	1.15
1.425 V	0.82	0.84	0.90	0.94	1.00	1.04	1.13
1.5 V	0.78	0.80	0.85	0.89	0.95	0.98	1.07
1.575 V	0.74	0.76	0.81	0.85	0.90	0.94	1.02
1.6 V	0.73	0.75	0.80	0.84	0.89	0.92	1.01

Notes:

1. *The user can set the junction temperature in Designer software to be any integer value in the range of –55°C to 175°C.*
2. *The user can set the core voltage in Designer software to be any value between 1.4V and 1.6V.*

All timing numbers listed in this datasheet represent sample timing characteristics of Axcelerator devices. Actual timing delay values are design-specific and can be derived from the Timer tool in Microsemi's Designer software after place-and-route.

User-Defined Supply Pins

VREF **Supply Voltage**

Reference voltage for I/O banks. VREF pins are configured by the user from regular I/O pins; VREF pins are not in fixed locations. There can be one or more VREF pins in an I/O bank.

Global Pins

HCLKA/B/C/D **Dedicated (Hardwired) Clocks A, B, C and D**

These pins are the clock inputs for sequential modules or north PLLs. Input levels are compatible with all supported I/O standards. There is a P/N pin pair for support of differential I/O standards. Single-ended clock I/Os can only be assigned to the P side of a paired I/O. This input is directly wired to each R-cell and offers clock speeds independent of the number of R-cells being driven. When the HCLK pins are unused, it is recommended that they are tied to ground.

CLKE/F/G/H **Routed Clocks E, F, G, and H**

These pins are clock inputs for clock distribution networks or south PLLs. Input levels are compatible with all supported I/O standards. There is a P/N pin pair for support of differential I/O standards. Single-ended clock I/Os can only be assigned to the P side of a paired I/O. The clock input is buffered prior to clocking the R-cells. When the CLK pins are unused, Microsemi recommends that they are tied to ground.

JTAG/Probe Pins

PRA/B/C/D **Probe A, B, C and D**

The Probe pins are used to output data from any user-defined design node within the device (controlled with Silicon Explorer II). These independent diagnostic pins can be used to allow real-time diagnostic output of any signal path within the device. The pins' probe capabilities can be permanently disabled to protect programmed design confidentiality. The probe pins are of LVTTL output levels.

TCK **Test Clock**

Test clock input for JTAG boundary-scan testing and diagnostic probe (Silicon Explorer II).

TDI **Test Data Input**

Serial input for JTAG boundary-scan testing and diagnostic probe. TDI is equipped with an internal 10 kΩ pull-up resistor.

TDO **Test Data Output**

Serial output for JTAG boundary-scan testing.

TMS **Test Mode Select**

The TMS pin controls the use of the IEEE 1149.1 boundary-scan pins (TCK, TDI, TDO, TRST). TMS is equipped with an internal 10 kΩ pull-up resistor.

TRST **Boundary Scan Reset Pin**

The TRST pin functions as an active-low input to asynchronously initialize or reset the boundary scan circuit. The TRST pin is equipped with a 10 kΩ pull-up resistor.

Special Functions

LP **Low Power Pin**

The LP pin controls the low power mode of Axcelerator devices. The device is placed in the low power mode by connecting the LP pin to logic high. To exit the low power mode, the LP pin must be set Low. Additionally, the LP pin must be set Low during chip powering-up or chip powering-down operations. See "Low Power Mode" on page 2-106 for more details.

NC **No Connection**

This pin is not connected to circuitry within the device. These pins can be driven to any voltage or can be left floating with no effect on the operation of the device.

SSTL3

Stub Series Terminated Logic for 3.3 V is a general-purpose 3.3 V memory bus standard (JESD8-8). The Axcelerator devices support both classes of this standard. This requires a differential amplifier input buffer and a push-pull output buffer.

Class I

***Table 2-50* • DC Input and Output Levels**

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	**Max., V**	**Min., V**	**Max., V**	**Max., V**	**Min., V**	**mA**	**mA**
-0.3	VREF – 0.2	VREF +0.2	3.6	VREF – 0.6	VREF + 0.6	8	–8

AC Loadings

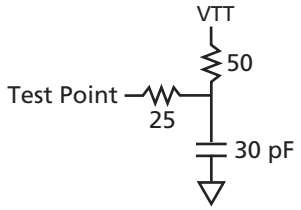


***Figure 2-23* • AC Test Loads**

***Table 2-51* • AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
VREF – 1.0	VREF + 1.0	VREF	1.50	30

*Note: *Measuring Point = VTRIP*

Timing Characteristics

***Table 2-52* • 3.3 V SSTL3 Class I I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
3.3 V SSTL3 Class I I/O Module Timing								
t_{DP}	Input Buffer		1.78		2.03		2.39	ns
t_{PY}	Output Buffer		2.17		2.47		2.91	ns
t_{ICLKQ}	Clock-to-Q for the I/O input register		0.67		0.77		0.90	ns
t_{OCLKQ}	Clock-to-Q for the I/O output register and the I/O enable register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Class II

Table 2-53 • DC Input and Output Levels

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA
-0.3	VREF – 0.2	VREF + 0.2	3.6	VREF – 0.8	VREF + 0.8	16	–16

AC Loadings

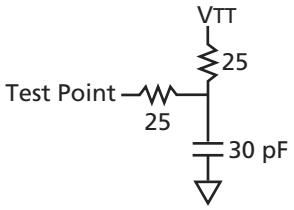


Figure 2-24 • AC Test Loads

Table 2-54 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
VREF – 1.0	VREF + 1.0	VREF	1.50	30

*Note: * Measuring Point = VTRIP*

Timing Characteristics

Table 2-55 • 3.3 V SSTL3 Class II I/O Module
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
3.3 V SSTL3 Class II I/O Module Timing								
t_{DP}	Input Buffer		1.85		2.10		2.47	ns
t_{PY}	Output Buffer		2.17		2.47		2.91	ns
t_{ICLKQ}	Clock-to-Q for the I/O input register		0.67		0.77		0.90	ns
t_{OCLKQ}	Clock-to-Q for the I/O output register and the I/O enable register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Vertical and Horizontal Routing

Vertical and Horizontal Tracks provide both local and long distance routing (Figure 2-37 on page 2-62). These tracks are composed of both short-distance, segmented routing and across-chip routing tracks (segmented at core tile boundaries). The short-distance, segmented routing resources can be concatenated through antifuse connections to build longer routing tracks.

These short-distance routing tracks can be used within and between SuperClusters or between modules of non-adjacent SuperClusters. They can be connected to the Output Tracks and to any logic module input (R-cell, C-cell, Buffer, and TX module).

The across-chip horizontal and vertical routing provides long-distance routing resources. These resources interface with the rest of the routing structures through the RX and TX modules (Figure 2-37). The RX module is used to drive signals from the across-chip horizontal and vertical routing to the Output Tracks within the SuperCluster. The TX module is used to drive vertical and horizontal across-chip routing from either short-distance horizontal tracks or from Output Tracks. The TX module can also be used to drive signals from vertical across-chip tracks to horizontal across-chip tracks and vice versa.

Figure 2-36 • **FastConnect Routing**

Figure 2-37 • **Horizontal and Vertical Tracks**

Figure 2-63 illustrates flag generation.

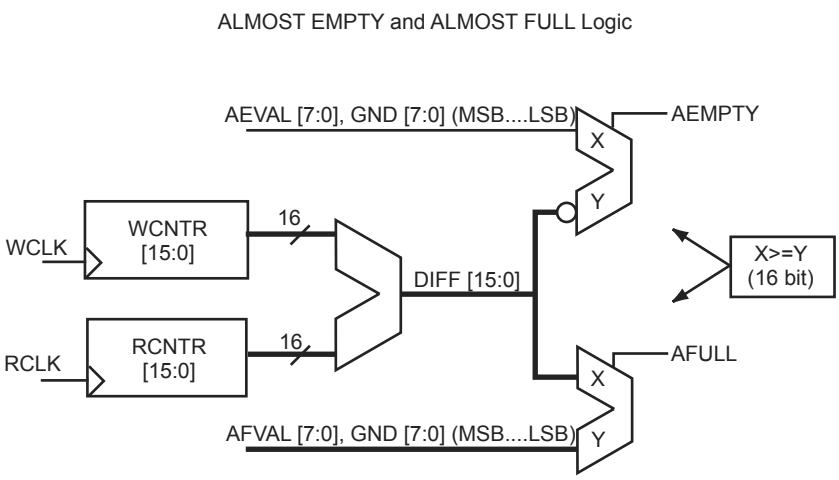


Figure 2-63 • **ALMOST-EMPTY and ALMOST-FULL Logic**

The Verilog codes for the flags are:

```
assign AF = (DIFF[15:0] >={AFVAL[7:0],8'b00000000})?1:0;
assign AE = ({AEVAL[7:0],8'b00000000}>=DIFF[15:0])?1:0;
```

The number of DIFF-bits active depends on the configuration depth and width (Table 2-95).

Table 2-95 • **Number of Available Configuration Bits**

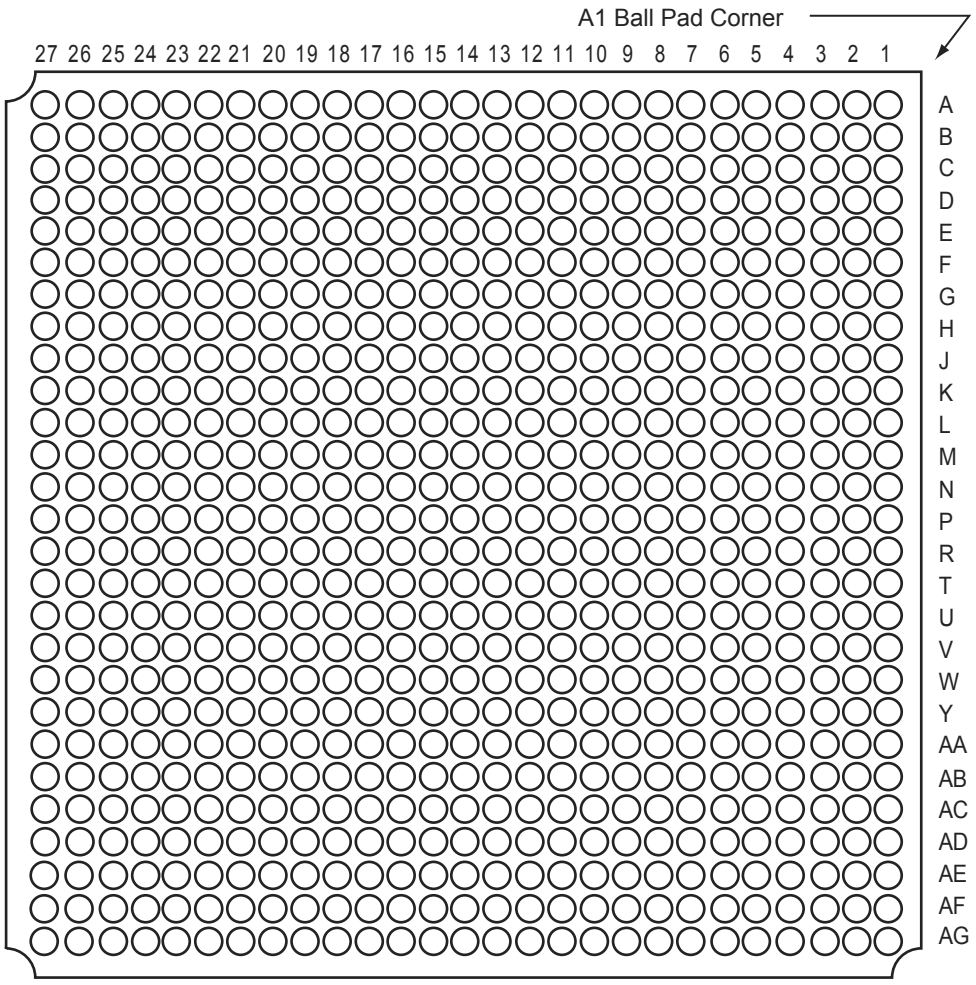
Number of Blocks	Block DxW	Number of AEVAL/AFVAL Bits
1	1x1	4
2	1x2	4
2	2x1	5
4	1x4	4
4	2x2	5
4	4x1	6
8	1x8	4
8	2x4	5
8	4x2	6
8	8x1	7
16	1x16	4
16	2x8	5
16	4x4	6
16	8x2	7
16	16x1	8

The active-high CLR pin is used to reset the FIFO to the empty state, which sets FULL and AFULL low, and EMPTY and AEMPTY high.

Assuming that the EMPTY flag is not set, new data is read from the FIFO when REN is valid on the active edge of the clock. Write and read transfers are described with timing requirements in "Timing Characteristics" on page 2-100.

3 – Package Pin Assignments

BG729



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

BG729	
AX1000 Function	Pin Number
IO54PB1F5	E20
IO55NB1F5	E21
IO55PB1F5	D21
IO56NB1F5	H19
IO56PB1F5	G19
IO57NB1F5	D22
IO57PB1F5	C22
IO58NB1F5	B23
IO58PB1F5	A23
IO59NB1F5	D23
IO59PB1F5	C23
IO60NB1F5	G21
IO60PB1F5	G20
IO61NB1F5	E23
IO61PB1F5	E22
IO62NB1F5	F22
IO62PB1F5	F21
IO63NB1F5	H20
IO63PB1F5	J19
Bank 2	
IO64NB2F6	J21
IO64PB2F6	H21
IO65NB2F6	F24
IO65PB2F6	F23
IO66NB2F6	F26
IO66PB2F6	F25
IO67NB2F6	E26
IO67PB2F6	E25
IO68NB2F6	J22
IO68PB2F6	H22
IO69NB2F6	G24
IO69PB2F6	G23
IO70NB2F6	K20
IO70PB2F6	J20
IO71NB2F6	G26
IO71PB2F6	G25
IO72NB2F6	J24

BG729	
AX1000 Function	Pin Number
IO72PB2F6	J23
IO73NB2F6	H24
IO73PB2F6	H23
IO74NB2F7	L21
IO74PB2F7	K21
IO75NB2F7	G27
IO75PB2F7	F27
IO76NB2F7	K23
IO76PB2F7	K22
IO77NB2F7	H26
IO77PB2F7	H25
IO78NB2F7	K25
IO78PB2F7	K24
IO79NB2F7	J26
IO79PB2F7	J25
IO80NB2F7	M20
IO80PB2F7	L20
IO81NB2F7	J27
IO81PB2F7	H27
IO82NB2F7	L23
IO82PB2F7	L22
IO83NB2F7	L25
IO83PB2F7	L24
IO84NB2F7	N21
IO84PB2F7	M21
IO85NB2F8	K27
IO85PB2F8	K26
IO86NB2F8	M23
IO86PB2F8	M22
IO87NB2F8	M25
IO87PB2F8	M24
IO88NB2F8	L27
IO88PB2F8	L26
IO89NB2F8	M27
IO89PB2F8	M26
IO90NB2F8	N23
IO90PB2F8	N22

BG729	
AX1000 Function	Pin Number
IO91NB2F8	N25
IO91PB2F8	N24
IO92NB2F8	N27
IO92PB2F8	N26
IO93NB2F8	P26
IO93PB2F8	P27
IO94NB2F8	N19
IO94PB2F8	N20
IO95NB2F8	P23
IO95PB2F8	P22
Bank 3	
IO96NB3F9	P25
IO96PB3F9	P24
IO97NB3F9	R26
IO97PB3F9	R27
IO98NB3F9	P21
IO98PB3F9	P20
IO99NB3F9	R24
IO99PB3F9	R25
IO100NB3F9	T26
IO100PB3F9	T27
IO101NB3F9	T24
IO101PB3F9	T25
IO102NB3F9	R20
IO102PB3F9	R21
IO103NB3F9	R23
IO103PB3F9	R22
IO104NB3F9	U26
IO104PB3F9	U27
IO105NB3F9	U24
IO105PB3F9	U25
IO106NB3F9	R19
IO106PB3F9	P19
IO107NB3F10	V26
IO107PB3F10	V27
IO108NB3F10	T23
IO108PB3F10	T22

FG256-Pin FBGA	
AX125 Function	**Pin Number**
VCCA	L10
VCCA	L7
VCCA	L8
VCCA	L9
VCCA	N3
VCCA	P14
VCCPLA	C7
VCCPLB	D6
VCCPLC	A10
VCCPLD	D10
VCCPLE	P10
VCCPLF	N11
VCCPLG	T7
VCCPLH	N7
VCCDA	A2
VCCDA	C13
VCCDA	D9
V_{CCDA}	H1
VCCDA	J15
VCCDA	N14
VCCDA	N8
VCCDA	P4
VCCIB0	E6
VCCIB0	E7
VCCIB0	E8
VCCIB1	E10
VCCIB1	E11
VCCIB1	E9
VCCIB2	F12
VCCIB2	G12
VCCIB2	H12
VCCIB3	J12
VCCIB3	K12
VCCIB3	L12
VCCIB4	M10

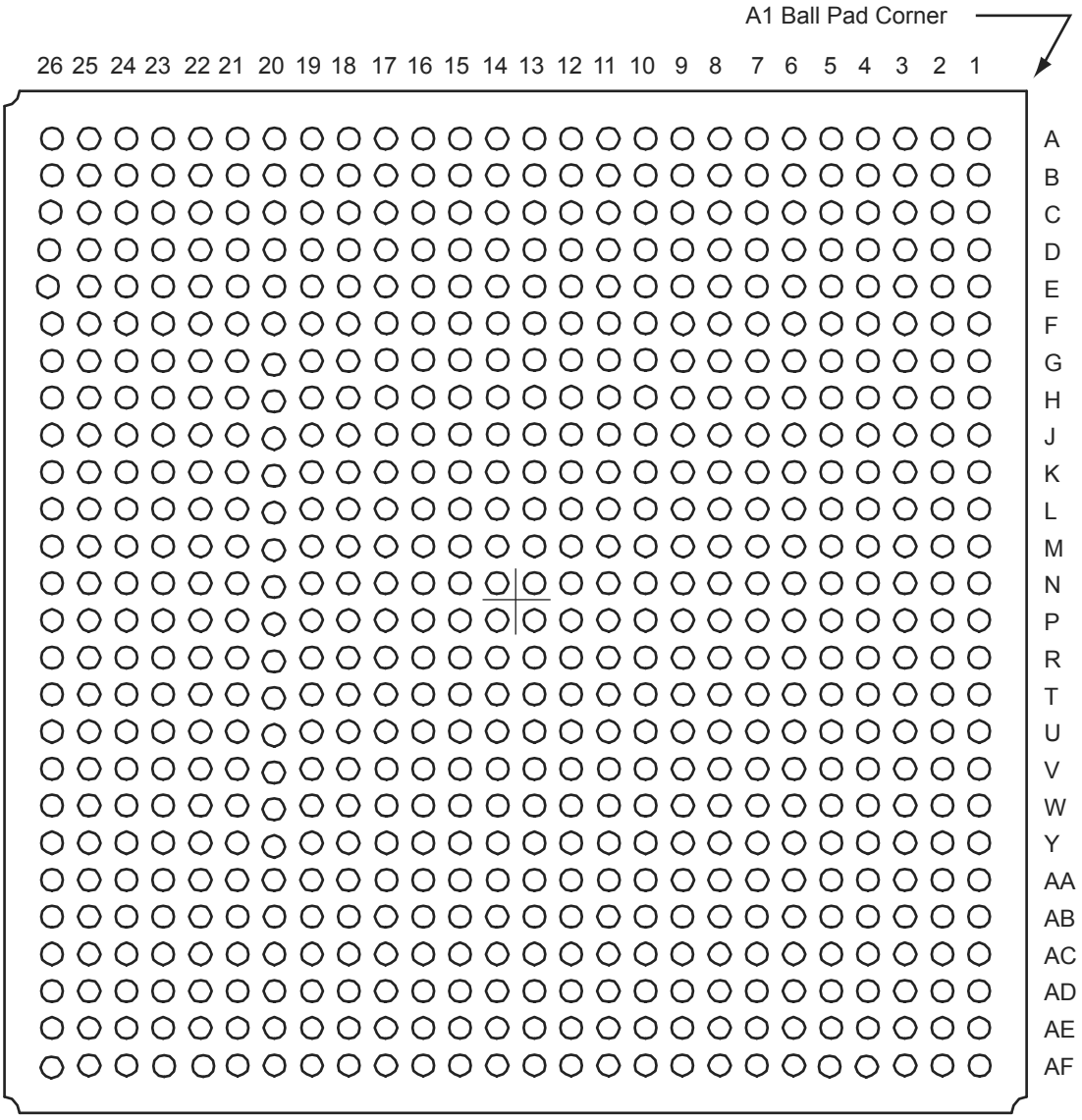
FG256-Pin FBGA	
AX125 Function	**Pin Number**
VCCIB4	M11
VCCIB4	M9
VCCIB5	M6
VCCIB5	M7
VCCIB5	M8
VCCIB6	J5
VCCIB6	K5
VCCIB6	L5
VCCIB7	F5
VCCIB7	G5
VCCIB7	H5
VCOMPLA	A7
VCOMPLB	D7
VCOMPLC	B9
VCOMPLD	D11
VCOMPLE	T10
VCOMPLF	N10
VCOMPLG	R8
VCOMPLH	N6
VPUMP	A14

FG484	
AX500 Function	**Pin Number**
IO163NB7F15	G5
IO163PB7F15	G6
IO164NB7F15	D1
IO164PB7F15	E1
IO165NB7F15	F4
IO165PB7F15	G4
IO166NB7F15	D2
IO166PB7F15	E2
IO167NB7F15	F5
IO167PB7F15	E4
Dedicated I/O	
VCCDA	H7
GND	A1
GND	A11
GND	A12
GND	A2
GND	A21
GND	A22
GND	AA1
GND	AA2
GND	AA21
GND	AA22
GND	AB1
GND	AB11
GND	AB12
GND	AB2
GND	AB21
GND	AB22
GND	B1
GND	B2
GND	B21
GND	B22
GND	C20
GND	C3
GND	D19

FG484	
AX500 Function	**Pin Number**
GND	D4
GND	E18
GND	E5
GND	G18
GND	H15
GND	H8
GND	J14
GND	J9
GND	K10
GND	K11
GND	K12
GND	K13
GND	L1
GND	L10
GND	L11
GND	L12
GND	L13
GND	L22
GND	M1
GND	M10
GND	M11
GND	M12
GND	M13
GND	M22
GND	N10
GND	N11
GND	N12
GND	N13
GND	P14
GND	P9
GND	R15
GND	R8
GND	U16
GND	U6
GND	V18

FG484	
AX500 Function	**Pin Number**
GND	V5
GND	W19
GND	W4
GND	Y20
GND	Y3
GND/LP	G7
NC	AB8
NC	AB16
NC	C10
NC	C11
NC	C14
PRA	G11
PRB	F11
PRC	T12
PRD	U12
TCK	G8
TDI	F9
TDO	F7
TMS	F6
TRST	F8
VCCA	G17
VCCA	J10
VCCA	J11
VCCA	J12
VCCA	J13
VCCA	J7
VCCA	K14
VCCA	K9
VCCA	L14
VCCA	L9
VCCA	M14
VCCA	M9
VCCA	N14
VCCA	N9
VCCA	P10

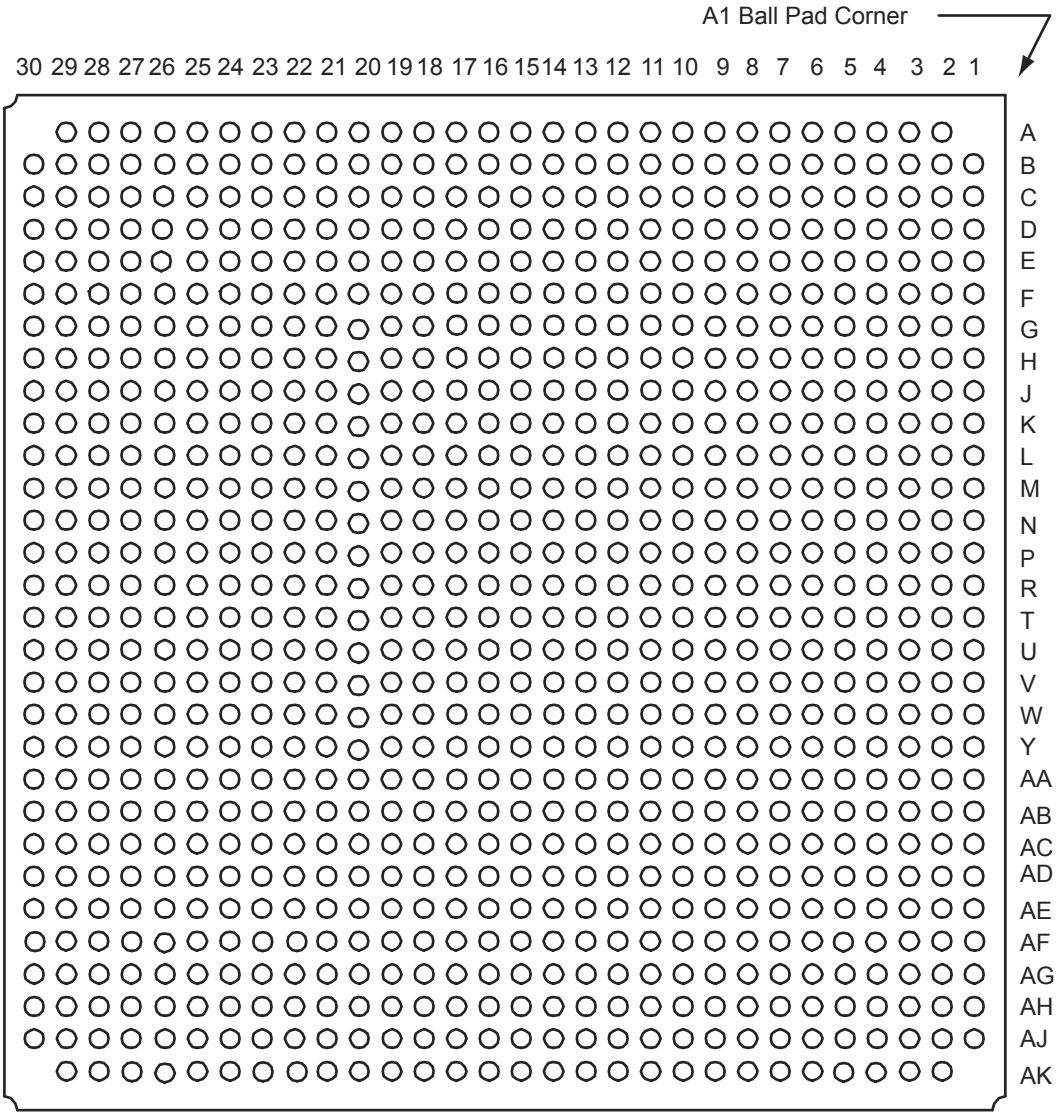
FG676



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

FG896



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

FG1152	
AX2000 Function	Pin Number
GND	AK12
GND	AK17
GND	AK18
GND	AK23
GND	AK30
GND	AK5
GND	AL1
GND	AL11
GND	AL2
GND	AL24
GND	AL3
GND	AL31
GND	AL32
GND	AL33
GND	AL34
GND	AL4
GND	AM1
GND	AM10
GND	AM15
GND	AM2
GND	AM20
GND	AM25
GND	AM3
GND	AM31
GND	AM32
GND	AM33
GND	AM34
GND	AM4
GND	AN1
GND	AN2
GND	AN26
GND	AN3
GND	AN31
GND	AN32
GND	AN33

FG1152	
AX2000 Function	Pin Number
GND	AN34
GND	AN4
GND	AN9
GND	AP13
GND	AP2
GND	AP22
GND	AP27
GND	AP3
GND	AP31
GND	AP32
GND	AP33
GND	AP4
GND	AP8
GND	B1
GND	B2
GND	B26
GND	B3
GND	B31
GND	B32
GND	B33
GND	B34
GND	B4
GND	B9
GND	C1
GND	C10
GND	C15
GND	C2
GND	C20
GND	C25
GND	C3
GND	C31
GND	C32
GND	C33
GND	C34
GND	C4

FG1152	
AX2000 Function	Pin Number
GND	D1
GND	D11
GND	D2
GND	D24
GND	D3
GND	D31
GND	D32
GND	D33
GND	D34
GND	D4
GND	E12
GND	E17
GND	E18
GND	E23
GND	E30
GND	E5
GND	F29
GND	F30
GND	F6
GND	G28
GND	G7
GND	H1
GND	H34
GND	J2
GND	J33
GND	K3
GND	K32
GND	L11
GND	L24
GND	L31
GND	L4
GND	M12
GND	M23
GND	M30
GND	M5

FG1152	
AX2000 Function	Pin Number
GND	N1
GND	N13
GND	N22
GND	N34
GND	P14
GND	P15
GND	P16
GND	P17
GND	P18
GND	P19
GND	P20
GND	P21
GND	R14
GND	R15
GND	R16
GND	R17
GND	R18
GND	R19
GND	R20
GND	R21
GND	R3
GND	R32
GND	T14
GND	T15
GND	T16
GND	T17
GND	T18
GND	T19
GND	T20
GND	T21
GND	U14
GND	U15
GND	U16
GND	U17
GND	U18

FG1152	
AX2000 Function	Pin Number
GND	U19
GND	U20
GND	U21
GND	U30
GND	U5
GND	V14
GND	V15
GND	V16
GND	V17
GND	V18
GND	V19
GND	V20
GND	V21
GND	V30
GND	V5
GND	W14
GND	W15
GND	W16
GND	W17
GND	W18
GND	W19
GND	W20
GND	W21
GND	Y14
GND	Y15
GND	Y16
GND	Y17
GND	Y18
GND	Y19
GND	Y20
GND	Y21
GND	Y3
GND	Y32
GND/LP	G6
NC	A17

FG1152	
AX2000 Function	Pin Number
NC	A26
NC	AB2
NC	AB33
NC	AC34
NC	AD3
NC	AD34
NC	AE31
NC	AE33
NC	AE34
NC	AF1
NC	AF34
NC	AG2
NC	AG4
NC	AH1
NC	AH2
NC	AH31
NC	AH32
NC	AH34
NC	AJ1
NC	AJ2
NC	AJ3
NC	AJ31
NC	AJ32
NC	AJ33
NC	AJ34
NC	AJ4
NC	AL29
NC	AM19
NC	AM7
NC	AN13
NC	AN17
NC	AN25
NC	AN27
NC	AN8
NC	AP17

FG1152	
AX2000 Function	**Pin Number**
VCOMPLD	K18
VCOMPLE	AH19
VCOMPLF	AF18
VCOMPLG	AH16
VCOMPLH	AD17
VPUMP	J26

CQ256	
AX2000 Function	**Pin Number**
VCCA	4
VCCA	22
VCCA	42
VCCA	61
VCCA	63
VCCA	84
VCCA	108
VCCA	127
VCCA	131
VCCA	150
VCCA	170
VCCA	189
VCCA	191
VCCA	212
VCCA	238
VCCDA	2
VCCDA	32
VCCDA	66
VCCDA	67
VCCDA	86
VCCDA	87
VCCDA	94
VCCDA	95
VCCDA	96
VCCDA	106
VCCDA	107
VCCDA	126
VCCDA	130
VCCDA	160
VCCDA	194
VCCDA	196
VCCDA	214
VCCDA	215
VCCDA	222
VCCDA	223

CQ256	
AX2000 Function	**Pin Number**
VCCDA	224
VCCDA	236
VCCDA	237
VCCDA	251
VCCIB0	230
VCCIB0	244
VCCIB1	200
VCCIB1	206
VCCIB1	218
VCCIB2	164
VCCIB2	176
VCCIB2	182
VCCIB3	138
VCCIB3	144
VCCIB3	156
VCCIB4	102
VCCIB4	114
VCCIB4	120
VCCIB5	72
VCCIB5	78
VCCIB5	90
VCCIB6	36
VCCIB6	48
VCCIB6	54
VCCIB7	10
VCCIB7	16
VCCIB7	28
VPUMP	195

CG624	
AX1000 Function	Pin Number
GND	A8
GND	AA10
GND	AA16
GND	AA18
GND	AA21
GND	AA5
GND	AB22
GND	AB4
GND	AC10
GND	AC16
GND	AC23
GND	AC3
GND	AD1
GND	AD2
GND	AD24
GND	AD25
GND	AE1
GND	AE18
GND	AE2
GND	AE24
GND	AE25
GND	AE8
GND	B1
GND	B2
GND	B24
GND	B25
GND	C10
GND	C16
GND	C23
GND	C3
GND	D22
GND	D4
GND	E10
GND	E16
GND	E21
GND	E5

CG624	
AX1000 Function	Pin Number
GND/LP	E8
GND	H1
GND	H21
GND	H25
GND	K21
GND	K23
GND	K3
GND	L11
GND	L12
GND	L13
GND	L14
GND	L15
GND	M11
GND	M12
GND	M13
GND	M14
GND	M15
GND	N11
GND	N12
GND	N13
GND	N14
GND	N15
GND	P11
GND	P12
GND	P13
GND	P14
GND	P15
GND	R11
GND	R12
GND	R13
GND	R14
GND	R15
GND	T21
GND	T23
GND	T3
GND	T5

CG624	
AX1000 Function	Pin Number
GND	V1
GND	V25
GND	V5
NC	A14
NC	AA20
NC	AB13
NC	AD4
NC	AE12
NC	F21
NC	G10
PRA	F13
PRB	A13
PRC	AB12
PRD	AE13
TCK	F5
TDI	C5
TDO	F6
TMS	D6
TRST	E6
VCCA	AB20
VCCA	F22
VCCA	F4
VCCA	J17
VCCA	J9
VCCA	K10
VCCA	K11
VCCA	K15
VCCA	K16
VCCA	L10
VCCA	L16
VCCA	R10
VCCA	R16
VCCA	T10
VCCA	T11
VCCA	T15
VCCA	T16

CG624	
AX2000 Function	**Pin Number**
Bank 0	
IO00NB0F0	D7*
IO00PB0F0	E7*
IO01NB0F0	G7
IO01PB0F0	G6
IO02NB0F0	B5
IO02PB0F0	B4
IO04PB0F0	C7
IO05NB0F0	F8
IO05PB0F0	F7
IO06NB0F0	H8
IO06PB0F0	H7
IO11NB0F0	J8
IO11PB0F0	J7
IO12PB0F1	B6
IO13NB0F1	E9*
IO13PB0F1	D8*
IO15NB0F1	C9
IO15PB0F1	C8
IO16NB0F1	A5
IO16PB0F1	A4
IO17NB0F1	D10
IO17PB0F1	D9
IO18NB0F1	A7
IO18PB0F1	A6
IO19NB0F1	G9
IO19PB0F1	G8
IO20PB0F1	B7
IO23NB0F2	F10
IO23PB0F2	F9
IO26NB0F2	C11*
IO26PB0F2	B8*

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

CG624	
AX2000 Function	**Pin Number**
IO27NB0F2	H10
IO27PB0F2	H9
IO28NB0F2	A9
IO28PB0F2	B9
IO30NB0F2	B11
IO30PB0F2	B10
IO31NB0F2	E11
IO31PB0F2	F11
IO33NB0F2	D12
IO33PB0F2	D11
IO34NB0F3	A11
IO34PB0F3	A10
IO37NB0F3	J13
IO37PB0F3	K13
IO38NB0F3	H11
IO38PB0F3	G11
IO40PB0F3	B12
IO41NB0F3/HCLKAN	G13
IO41PB0F3/HCLKAP	G12
IO42NB0F3/HCLKBN	C13
IO42PB0F3/HCLKBP	C12
Bank 1	
IO43NB1F4/HCLKCN	G15
IO43PB1F4/HCLKCP	G14
IO44NB1F4/HCLKDN	B14
IO44PB1F4/HCLKDP	B13
IO45NB1F4	H13
IO47NB1F4	D14
IO47PB1F4	C14
IO48NB1F4	A16
IO48PB1F4	A15
IO49PB1F4	H15

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

CG624	
AX2000 Function	**Pin Number**
IO51NB1F4	E15
IO51PB1F4	F15
IO52NB1F4	A17
IO55NB1F5	G16
IO55PB1F5	H16
IO56NB1F5	A20
IO56PB1F5	A19
IO57NB1F5	D16
IO57PB1F5	D15
IO58NB1F5	A22
IO58PB1F5	A21
IO59NB1F5	F16
IO61NB1F5	G17
IO61PB1F5	H17
IO62NB1F5	B17
IO62PB1F5	B16
IO63NB1F5	H18
IO65NB1F6	C17
IO66PB1F6	B18
IO67NB1F6	J18
IO67PB1F6	J19
IO68NB1F6	B20
IO68PB1F6	B19
IO69NB1F6	E17
IO69PB1F6	F17
IO70NB1F6	B22
IO70PB1F6	B21
IO71PB1F6	G18
IO73NB1F6	G19
IO74NB1F6	C19
IO74PB1F6	C18
IO75NB1F6	D18

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

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